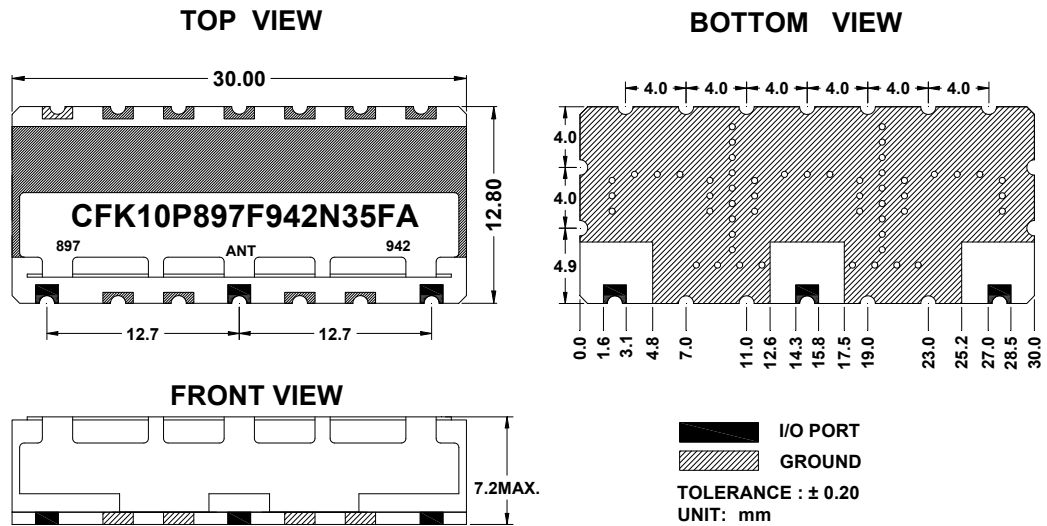


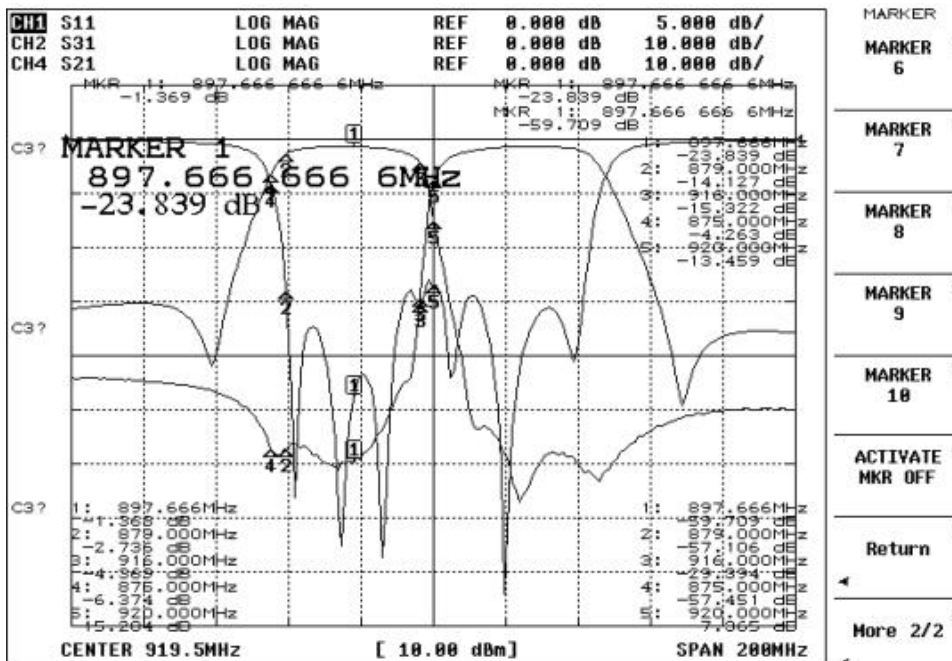
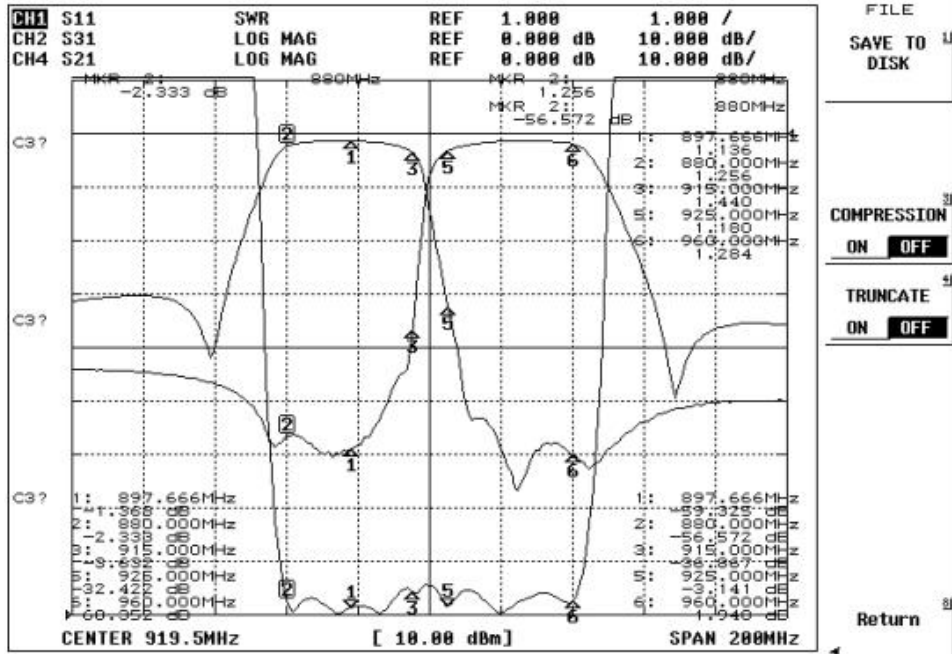
Electrical Specification

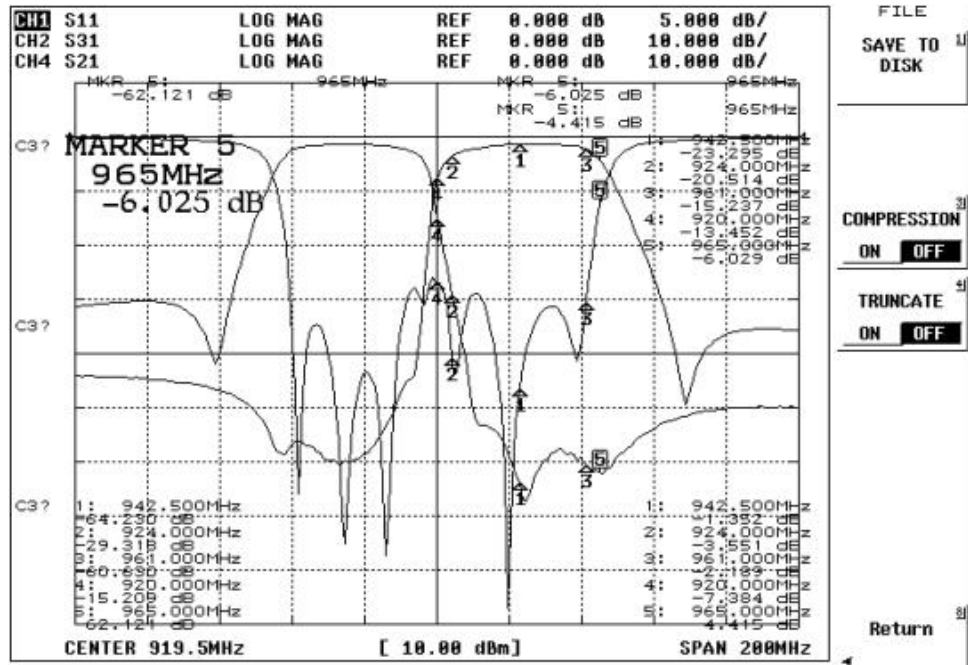
ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	897.5	942.5	MHz
Bandwidth [BW]	fo ±17.5 [880.0~915.0]	fo ±17.5 [925.0~960.0]	MHz
Insertion Loss in BW	4.0	4.0	dB max
Ripple in BW	3.5	3.5	dB max
Return Loss in BW	10.0	10.0	dB min
Attenuation <input type="checkbox"/> Absolute Value <input checked="" type="checkbox"/> Relative Value	30.0dBc min.@[925.0~960.0]	30.0dBc min.@[925.0~960.0]	MHz
	0.5 dBc min. @ [879 & 916]	0.5 dBc min. @ [879 & 916]	MHz
	2.0dBc min.@ [875.0&920.0]	2.0dBc min.@ [875.0&920.0]	MHz
	dBc min. @ [&]	dBc min. @ [&]	MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

Mechanical Specification

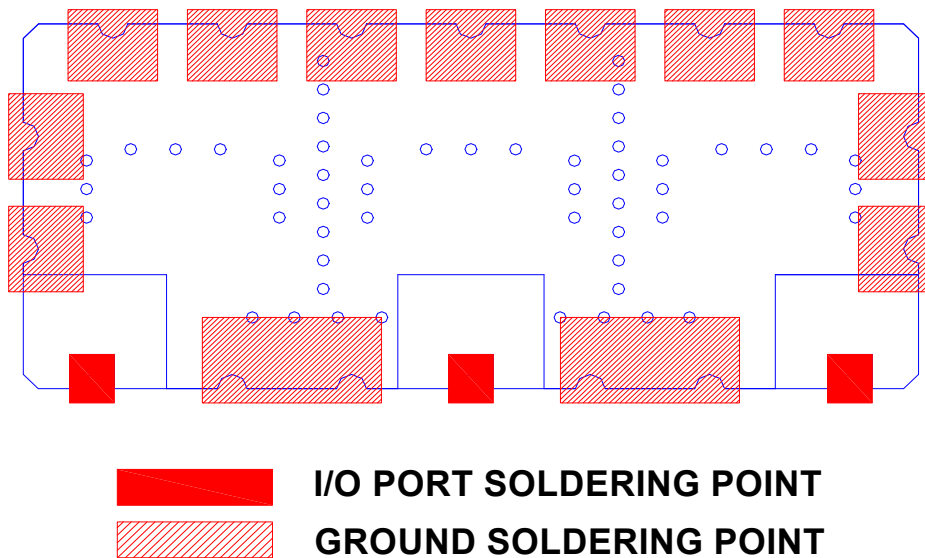


Plot Data

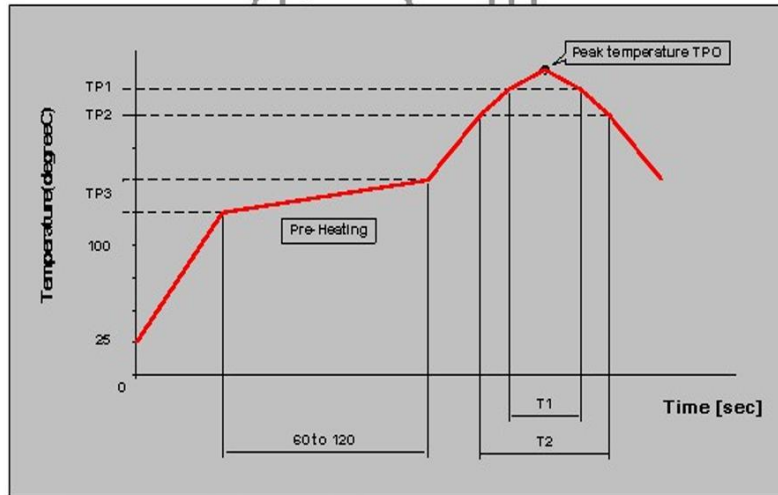




Recommended PC Board Pattern



 Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±/5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180